MSKSEMI 美森科













ESD

TVS

TSS

MOV

GDT

PLED

GBU10005-MS THRU GBU1010-MS

Product specification



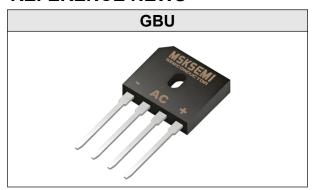


VOLTAGE RANGE: 50 - 1000V CURRENT: 10 A

FEATURES

- Ideal for printed circuit board
- Low forward voltage
- Low leakage current
- Polarity: marked on body
- Mounting position: Any

REFERENCE NEWS



Marking

GBU10005-MS	GBU1001-MS	GBU1002-MS	GBU1004-MS
MSKSEMI GBU 10005 + AC -	MSKSEMI GBU 1001 + AC -	MSKSEMI GBU 1002 + AC -	GBU 1004
GBU1006-MS	GBU1008-MS	GBU1010-MS	
MSKSEMI GBU 1006 + AC -	MSKSEMI GBU 1008 + AC -	GBU 1010	

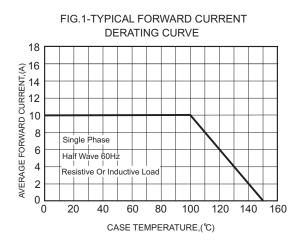
MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

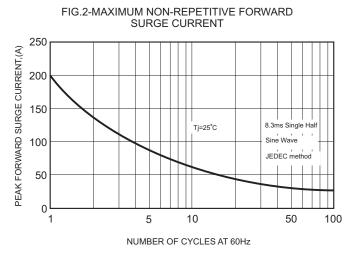
Rating 25° C ambient temperature uniess otherwies specified. Single phase half wave, 60Hz, resistive or inductiveload. For capacitive load, derate current by 20%.

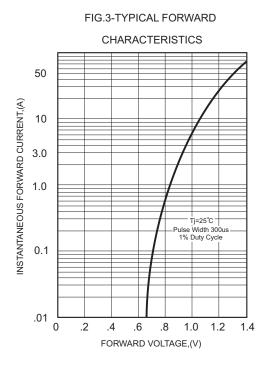
TYPE NUMBER	GBU10005 -MS	GBU1001 -MS	GBU1002 -MS	GBU1004 -MS	GBU106 -MS	GBU1008 -MS	GBU1010 -MS	UNITS
Maximum Recurrent Peak Reverse Voltage	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current. 375"(9.5mm) Lead Length at Tc=70℃	10						А	
Peak Forward Surge Current, 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	200						Α	
Maximum Forward Voltage Drop per Bridge Element at 5.04 D.C.	1.1						V	
Maximum DC Reverse Current at Ta=25°C				5.0				μA
Rated DC Blocking Voltage Ta=100°C	500						μΑ	
Operating Temperature Range, TJ	-65 to + 150						${\mathbb C}$	
Storage Temperature Range, Tstg	-65 to + 150						$^{\circ}$	

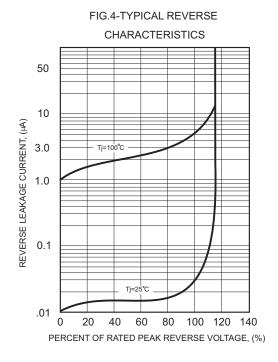


RATINGAND CHARACTERISTIC CURVES (GBU10005-MS THRU GBU1010-MS)



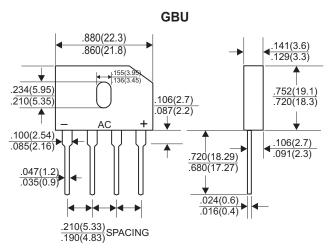








PACKAGE MECHANICAL DATA



Dimensions in inches and (millimeters)

REELSPECIFICATION

P/N	PKG	QTY
GBU10005-MS THRU GBU1010-MS	GBU	500



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